Dual N-Channel PowerTrench[®] MOSFET

30 V, 28 A, 2.12 m Ω

General Description

This package integrates two N–Channel devices connected internally in common–source configuration. This enables very low package parasitics and optimized thermal path to the common source pad on the bottom. Provides a very small footprint $(3.3 \times 5 \text{ mm})$ for higher power density.

Features

- Max $r_{DS(on)} = 2.12 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 28 \text{ A}$
- Max $r_{DS(on)} = 2.95 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 24 \text{ A}$
- Ideal for Flexible Layout in Secondary Side Synchronous Rectification
- 100% UIL Tested
- Termination is Lead-free and RoHS Compliant

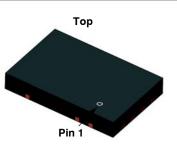
Applications

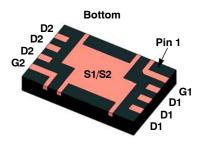
- Isolated DC-DC Synchronous Rectifiers
- Common Ground Load Switches



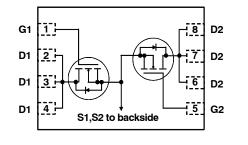
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PQFN8 PowerTrench CASE 483AU



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

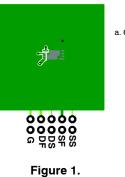
Table 1. MOSFET MAXIMUM RATINGS	$T_A = 25^{\circ}C$ unless otherwise noted.
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Symbol	Parameter		Rating	Units	
V _{DS}	Drain to Source Voltage		30	V	
V _{GS}	Gate to Source Voltage		±20	V	
I _D	Drain Current -Continuous	T _C = 25°C (Note 1)	95	А	
	– Continuous	T _C = 100°C (Note 1)	60		
	– Continuous	$T_A = 25^{\circ}C$ (Figure 1)	28		
– Pulsed		(Note 2)	562		
E _{AS}	Single Pulse Avalanche Energy	(Note 3)	96	mJ	
PD	Power Dissipation	$T_{C} = 25^{\circ}C$	29	W	
	Power Dissipation	$T_A = 25^{\circ}C$ (Figure 1)	2.1		
T _J , T _{STG}	Operating and Storage Junction Temperature Range		–55 to +150	°C	

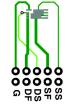
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electromechanical application board design.

2. Pulse Id refers to Figure 13 Forward Bias Safe Operating Area. 3. E_{AS} of 96 mJ is based on starting $T_J = 25^{\circ}C$; L = 0.3 mH, $I_{AS} = 31.7$ A, $V_{DD} = 27$ V.



a. 60 °C/W when mounted on a 12in pad of 2 oz copper



b.160 °C/W when mounted on a minimum pad of 2 oz copper

Figure 2.

Table 2. THERMAL CHARACTERISTICS

	$R_{\theta JC}$	Thermal Resistance, Junction to Case	4	.7	°C/W
ſ	$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Figu	re 1) 6	60	

R_{θJA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material, R_{θCA} is determined by the user's board design.

Table 3. PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMD8430	FDMD8430	Power 3.3 x 5	13″	12 mm	3000 units

Table 4. ELECTRICAL CHARACTERISTICS T_J = 25°C unless otherwise noted.

Symbol	I Parameter Test Conditions		Min	Тур	Max	Units			
OFF CHARA	OFF CHARACTERISTICS								
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V$	30			V			
$\Delta BV_{DSS/} \Delta T_J$	Breakdown Voltage Temperature Coefficient	I_D = 250 $\mu A,$ referenced to 25°C		17		mV/°C			
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ			
I _{GSS}	Gate to Source Leakage Current	$V_{GS}=\pm 20 \text{ V}, \text{ V}_{DS}=0 \text{ V}$			±100	nA			

ON CHARACTERISTICS

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \ \mu A$	1.0	1.6	3.0	V
$\Delta V_{GS(th)}$ / ΔT_{J}	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 $\mu A,$ referenced to 25°C		-5		mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 28 A		1.5	2.12	mΩ
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 24 \text{ A}$		2.0	2.95	
		V_{GS} = 10 V, I _D = 28 A, T _J = 125°C		1.7	2.4	
9 FS	Forward Transconductance	$V_{DD} = 5 \text{ V}, \text{ I}_{D} = 28 \text{ A}$			250	S

DYNAMIC CHARACTERISTICS

	C _{iss}	Input Capacitance	V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHZ	3595	5035	pF
	C _{oss}	Output Capacitance		1150	1610	pF
	C _{rss}	Reverse Transfer Capacitance		112	160	pF
Γ	Rg	Gate Resistance		2.3	4.5	Ω

SWITCHING CHARACTERISTICS

t _{d(on)}	Turn-On Delay Time	$V_{DD} = 15 \text{ V}, \text{ I}_{D} = 28$	A,		11	20	ns
t _r	Rise Time	$v_{GS} = 10 v, R_{GEN} =$	$V_{GS} = 10 \text{ V}, \overline{\text{R}}_{\text{GEN}} = 6 \Omega$		8	16	ns
t _{d(off)}	Turn-Off Delay Time				71	114	ns
t _f	Fall Time				20	36	ns
Q _{g(tot)}	Total Gate Charge	$V_{GS} = 0 V$ to 10 V	$ \begin{array}{c} V_{GS} = 0 \ V \ to \ 10 \ V \\ V_{GS} = 0 \ V \ to \ 4.5 \ V \\ \end{array} \\ \end{array} \begin{array}{c} V_{DD} = 15 \ V, \\ I_D = 28 \ A \end{array} $		52	90	nC
	Total Gate Charge	V_{GS} = 0 V to 4.5 V			25	45	nC
Q _{gs}	Gate to Source Charge				10		nC
Q _{gd}	Gate to Drain "Miller" Charge				7		nC

DRAIN-SOURCE DIODE CHARACTERISTICS

V _{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I _S = 28 A (Note 5)	0.8	1.2	V
t _{rr}	Reverse Recovery Time	I _F = 28 A, di/dt = 100 A/µs	40	64	ns
Q _{rr}	Reverse Recovery Charge		22	36	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 5. Pulse Test: Pulse Width < 300 µs, Duty Cycle < 2.0%.



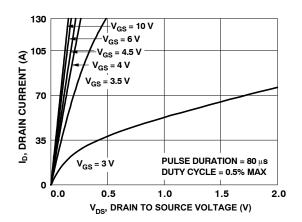


Figure 3. On Region Characteristics

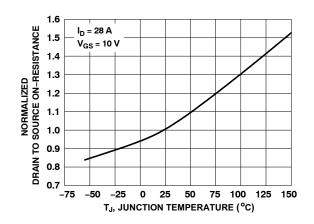


Figure 5. Normalized On–Resistance vs. Junction Temperature

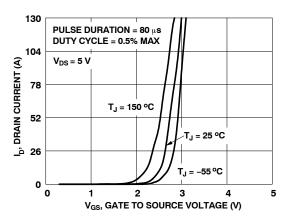
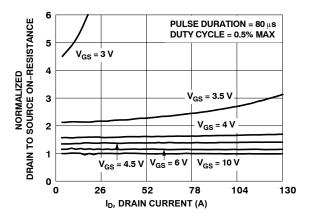
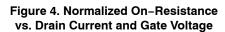


Figure 7. Transfer Characteristics





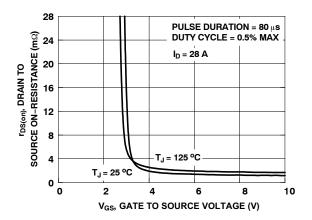


Figure 6. On–Resistance vs. Gate to Source Voltage

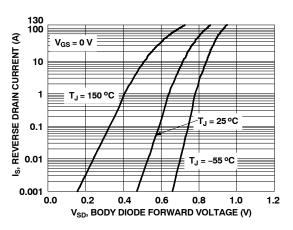


Figure 8. Source to Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS $T_J = 25^{\circ}C$ unless otherwise noted.

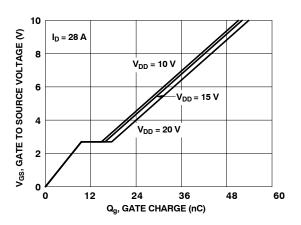
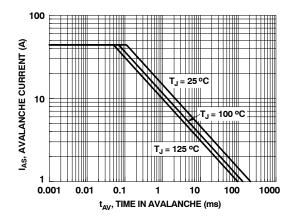
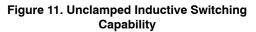


Figure 9. Gate Charge Characteristics





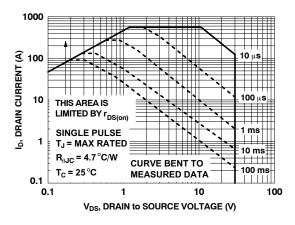


Figure 13. Forward Bias Safe Operating Area

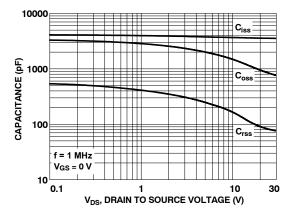


Figure 10. Capacitance vs. Drain to Source Voltage

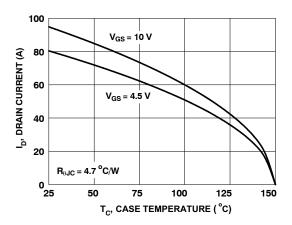


Figure 12. Maximum Continuous Drain Current vs. Case Temperature

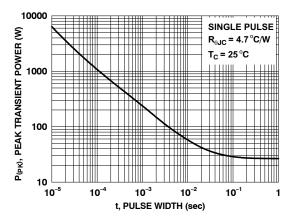


Figure 14. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS $T_J = 25^{\circ}C$ unless otherwise noted.

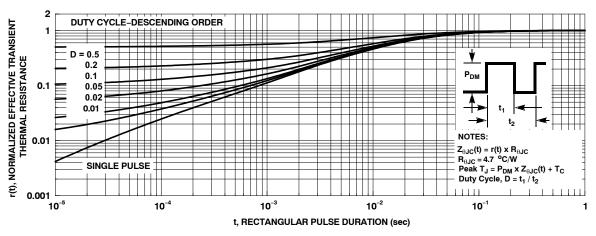
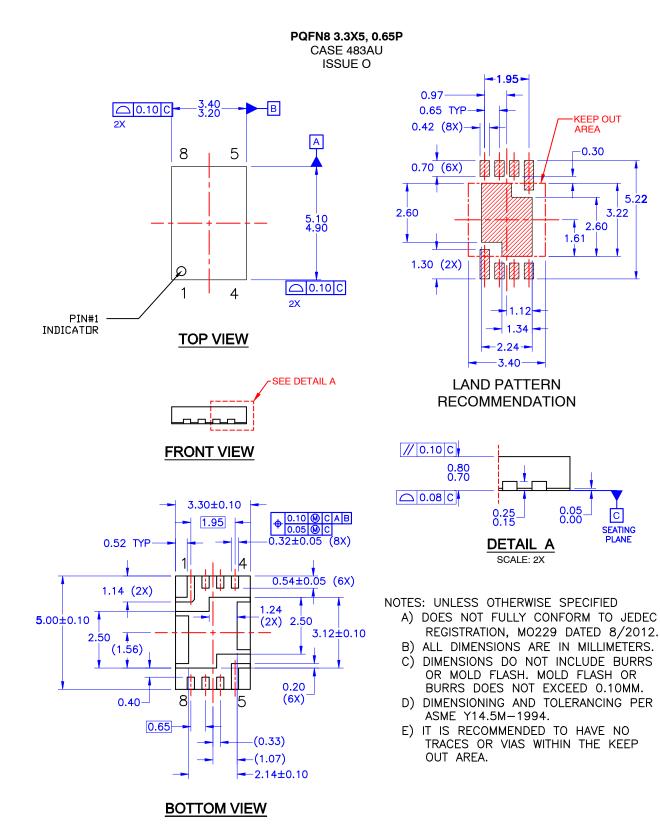


Figure 15. Junction-to-Case Transient Thermal Response Curve

PACKAGE DIMENSIONS



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